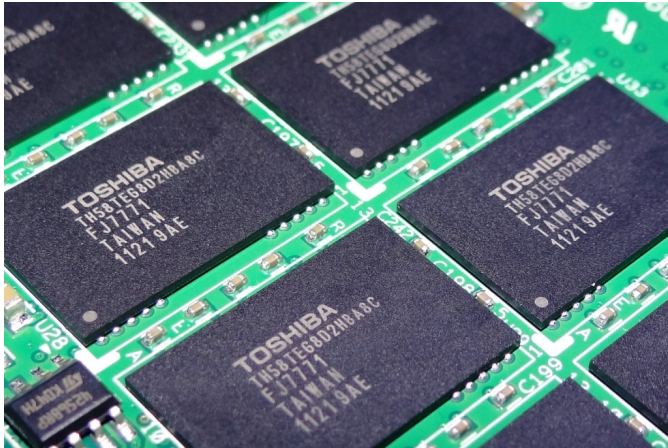


Second Gen 19nm NAND Flash from Toshiba

Written by Marco Attard
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Toshiba America Electronic Components (TAEC) launches an e-MMC compliant flash memory module range, using NAND chips fabricated via second generation 19nm technology.



The modules are designed for a wide variety of consumer applications, including smartphones, tablets and video cameras. All are compliant with JEDEC e-MMC version 5.0, achieve high read/write performance via HS400 interface standard and carry 64-Gigabit (equivalent to 8GB) 19nm NAND flash.

The package measures all of 11.5 x 13 x 1.0mm.

Mass production of 16 and 32GB modules kicks off from November 2013, with additional capacities (4, 8, 64, and 128GB) to follow.

Go [Toshiba Launches New Embedded NAND Flash Memory Modules](#)